

1st Call for papers

6th IMAPS flash Conference 2020

Dear Colleagues,

we invite you to submit a paper/abstract to **6th IMAPS flash Conference 2020**, which will take place in Brno, Czech Republic, on **October 22 – 23, 2020**.

IMAPS flash Conference is the European forum for the exchange of information between senior and young scientists from academic communities and electronic industries on topics related to their experimental and theoretical work in the very wide-spread field of electronics and microelectronics technology and packaging.

It is our pleasure to encourage you to participate in IMAPS flash Conference 2020, organized by International Microelectronics Assembly and Packaging Society Czech and Slovak Chapter (IMAPS CZ&SK), Brno University of Technology and Central European Institute of Technology (CEITEC).

Basic Conference Topics:

- Microelectronics Assembly
- Packaging & 3D Structures
- Soldering & Chip Attachment
- Simulation & Testing
- Sensors & Nanostructures

Workshop:

Announced later

Based on the author preference, the Scientific Committee recommendation and a standard journal reviewing procedure, the manuscript will be published in:

Singular edition of **Electroscope Journal (ISSN 1802-4564)**,

selected papers can be published in **Journal of Electrical Engineering (ISSN 1335-3632)**, impact factor **0.549**

The deadlines are the following:

Submission of Abstracts:	before 13.9. 2020
Notification of acceptance:	13.9.2020
Submission of Camera-ready papers and authors' registration:	27.9.220

Best regards,

6th IMAPS flash Conference 2020 Organizing Committee

Local Organization: Technical University of BRNO, Faculty of Electrical Engineering and Communication, Dept. Microelectronics
Postal address: CZ – 616 00 Brno, Technická 3058/10
<http://www.vutbr.cz/>



Media partner: DPS od A do Z

See you:

October 22 - 23, 2020

Brno, Czech Republic

cz.imapseurope.org